

Type number	Package	Package description	Total product weight
74AUP1G86GN	SOT1115	X2SON6	0.87054 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935291747132	4	1	260	30 s	1	240	20 s	3	Seremban, Malaysia; Bangkok, Thailand; Nijmegen, Netherlands	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.03146	100.00000	3.61327
		subTotal		0.03146	100.00000	3.61327
Component	Additive	Non hazardous	Proprietary	0.00025	5.00000	0.02872
	Filler	Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.00025	5.00000	0.02872
		Silica -amorphous-	7631-86-9	0.00250	50.00000	0.28718
		Epoxy resin system	Proprietary	0.00150	30.00000	0.17231
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.00050	10.00000	0.05744
		subTotal		0.00500	100.00000	0.57437
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.36386	94.51000	41.79745
		Magnesium (Mg)	7439-95-4	0.00058	0.15000	0.06634
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01136	2.95000	1.30465
		Silicon (Si)	7440-21-3	0.00246	0.64000	0.28304
	Pure metal layer	Gold (Au)	7440-57-5	0.00008	0.02000	0.00885
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00631	1.64000	0.72530
		Palladium (Pd)	7440-05-3	0.00035	0.09000	0.03980
subTotal		0.38500	100.00000	44.22543		
Mould Compound	Additive	Misc. Phosphor compounds (generic)	7723-14-0	0.00044	0.10000	0.04997
		Non hazardous	Proprietary	0.01566	3.60000	1.79888
	Filler	Silica fused	60676-86-0	0.38280	88.00000	43.97271
		Carbon black	1333-86-4	0.00087	0.20000	0.09994
	Polymer	Phenolic resin	Proprietary	0.01784	4.10000	2.04873
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.01740	4.00000	1.99876
subTotal		0.43500	100.00000	49.96899		
Wire	Gold alloy	Gold (Au)	7440-57-5	0.01395	99.00000	1.60235
		Palladium (Pd)	7440-05-3	0.00014	1.00000	0.01619
	subTotal		0.01409	100.00000	1.61854	

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.